Intel® Server Board SE7230CA1-E
Memory List Test Report Summary

Revision History		
Date	**Rev**	**Modifications**
May/06	1.0	Initial release.
Aug/06	2.0	Added TRS* and ATP Electronics* 512MB parts. (In shaded area)
Oct/06	3.0	Added Buffalo*, TRS, ATP Electronics, Ventura*, and Smart* 512MB parts. Added Ventura and Smart 1GB parts. (In shaded area)
Nov/06	4.0	Added Dataram* and Kingston* 512MB parts. Added Dataram and Smart 1GB parts. (In shaded area)
Jan/07	5.0	Added Micron and Qimonda 512MB parts. Added Micron, Qimonda, Kingston, ATP Electronics, and Ventura 1GB parts. (In shaded area)
Jan/07	6.0	Added TRS 2GB part. (In shaded area)
Feb/07	7.0	Added ATP Electronics 512MB part. Added TRS 1GB part. (In shaded area)
Feb/07	8.0	Added ATP Electronics 1GB part. (In shaded area)
Mar/07	9.0	Added ATP Electronics 2GB part. (In shaded area)
Mar/07	10.0	Updated contact information. No new parts added.
May/07	11.0	Added Smart 512MB part. Added Kingston 2GB part. (In shaded area)
May/07	12.0	Additional memory parts added. (In shaded area)
Jun/07	13.0	Additional memory parts added. (In shaded area)
Jul/07	14.0	Additional memory parts added. (In shaded area)
Aug/07	15.0	Additional memory parts added. (In shaded area)
Nov/07	16.0	Additional memory parts added. (In shaded area)

Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended.

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Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7230CA1-E. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)[1]. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel®'s Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft* Windows Server 2003* Enterprise Edition for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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[1] CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels.

CMTL contact:

Office: (949) 716-8690	Computer Memory Test Lab (CMTL)
Fax (949) 716-8691	24 Hammond Suite F
	Irvine, CA 92618
	http://www.cmtlabs.com/

Qualified Memory for the Intel® Server Board SE7230CA1-E

The memory module on the Intel® Server Board SE7230CA1-E has 4 DIMM sockets, which can hold up to 8 GB of Unbuffered ECC and non-ECC DDR2-400, DDR2-533 or DDR2-667 memory using four 72-bit DIMM modules. The following memory features are supported:

- DDR2-400, DDR2-533 and DDR-667 Unbuffered ECC and non-ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMMs with capacity of 256MB, 512MB, 1GB and 2GB. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 256MB using one 256MB DIMM.
- Maximum configuration is 4GB.

Below is a chart that lists the current supported memory types:

DDR2-400 Unbuffered SDRAM Module Matrix					
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Banks	# Address bits rows/Banks/column
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10
DDR2-533 Unbuffered SDRAM Module Matrix					
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Banks	# Address bits rows/Banks/column
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10
DDR2-667 Unbuffered SDRAM Module Matrix					
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Banks	# Address bits rows/Banks/column
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10

Memory features are detailed in *the Intel® Server Board SE7230CA1-E Technical Product Specification* available on-line at http://support.intel.com/support/motherboards/server/SE7230CA1-E

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7230CA1-E. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

Note: This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

This list is subject to change without notice.

Server Board SE7230CA1-E

Unbuffered, ECC, DDR2-400 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, ECC, DDR2-533 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, ECC, DDR2-667 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards.   For further information contact CMTL @ http://cmtlabs.com/

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Server Board SE7230CA1-E

Unbuffered, Non-ECC, DDR2-400 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-533 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-667 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

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Server Board SE7230CA1-E

Unbuffered, ECC, DDR2-400 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, ECC, DDR2-533 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
TRS	TRS30281X	HYB18T512800AF37 rev A	Qimonda (Infineon)	M0544LA1 rev 1	8/4/06	4	Yes	(64Mx8)*9	
TRS	TRS30282X	E5108AG-5C-E rev G	Elpida	M0544LA1 rev 1	8/9/06	4	Yes	(64Mx8)*9	
TRS	TRS30283X	K4T51083QC-ZCD5 rev C	Samsung	M0544LA1 rev 1	8/14/06	4	Yes	(64Mx8)*9	
TRS	TRS30282	E5108AG-5C-E rev G	Elpida	M0544LA1 rev 1	9/12/06	4	Yes	(64Mx8)*9	
TRS	TRS30281	HYB18T512800AF37 rev A	Qimonda (Infineon)	M0544LA1 rev 1	9/13/06	4	Yes	(64Mx8)*9	
TRS	TRS30283	K4T51083QC-ZCD5 rev C	Samsung	M0544LA1 rev 1	9/14/06	4	Yes	(64Mx8)*9	
Buffalo	D2U533B-ES512MDJ	MT47H64M8B6-37E rev D	Micron	2DUA18F-BA rev B	9/22/06	4	Yes	(64Mx8)*9	
Qimonda	HYS72T64000HU-3.7-A	HYB18T512800AF-3.7-A	Qimonda		12/1/06	4	Yes	(64Mx8)*9	
Micron	MT9HTF6472AY-53EB3	MT47H64M8CB-37E	Micron		12/1/06	4	Yes	(64Mx8)*9	

Unbuffered, ECC, DDR2-667 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72T64000HU-3S-A	HYB18T512800AF-3S-A	~ Qimonda (Infineon)		5/19/06	5	Yes	(64Mx8)*9	
Micron	MT9HTF6472AY-667B3	MT47H64M8BT-3	Micron		5/19/06	5	Yes	(64Mx8)*9	
Samsung	M391T6553CZ3-CE6	K4T510830C-ZCE6	Samsung		5/19/06	5	Yes	(64Mx8)*9	
ATP Electronics	AJ64K72F8BHE6S	K4T51083QC-ZCE6 rev C	Samsung		8/10/06	5		(64Mx8)*9	
ATP Electronics	AJ64K72F8BHE6S	K4T51083QC-ZCE6 rev C	Samsung	SJ240F08K1	8/10/06	5	Yes	(64Mx8)*9	
Ventura Technology Group	D2-52CD63LV-555	EDE5108AGBG-6E-E rev G	Elpida	D2U72F na	8/16/06	5	Yes	(64Mx8)*9	
Smart Modular Technologies	SG647UDR264852-SC	K4T51083QC-ZCE6 rev C	Samsung	M391T6553CZ0-V03 na	9/5/06	5	Yes	(64Mx8)*9	
Dataram	DTM63321C	NT5TU64M8AE-3C rev A	Nanya	40038A rev A	10/30/06	5	Yes	(64Mx8)*9	
Kingston	KVR667D2E5/512I	NT5TU64M8AE-3C rev A	Nanya	2025320-0F1.A00 na	11/7/06	5	Yes	(64Mx8)*9	

Unbuffered, ECC, DDR2-667 DIMM Modules 512MB Sizes (64Mx72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
Kingston	KVR667D2E5/512I	E5108AGSE(BG)-6E-E rev G	Elpida	2025320.0 F1.A00 na	11/8/06	5	Yes	(64Mx8)*9	
ATP Electronics	AJ64K72F8BHE6S	K4T51083QE-ZCE6 rev E	Samsung	D2U72F na	1/24/07	5	Yes	(64Mx8)*9	
Smart Modular Technologies	SG647UDR264852ES	GSW64M8XB3IT5X4GSE rev G	Smart	PG54G240 NUBUB1R F rev A	4/19/07	5	Yes	(64Mx8)*9	
Kingston	KVR667D2E5/512I	NT5TU64M8BE-3C rev B	Nanya	2025320-0F1.A00 na	5/10/07	5	Yes	(64Mx8)*9	

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Server Board SE7230CA1-E

Unbuffered, Non-ECC, DDR2-400 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-533 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
Dane-Elec	D2D533-064644NG	EDE5108AG-5C-E rev G	Elpida	D2U64D na	7/13/07	4	Yes	(64Mx8)*18	

Unbuffered, Non-ECC, DDR2-667 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

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Server Board SE7230CA1-E									
Unbuffered, ECC, DDR2-400 DIMM Modules **1GB Sizes (128Mx72)**									
Manufacturer	**Part Number**	**DRAM Part Number**	**DRAM Vendor**	**PCB Part Number**	**Date**	**CAS Latency**	**Lead Free**	**DRAM Organization**	**EOL**
Unbuffered, ECC, DDR2-533 DIMM Modules **1GB Sizes (128Mx72)**									
Manufacturer	**Part Number**	**DRAM Part Number**	**DRAM Vendor**	**PCB Part Number**	**Date**	**CAS Latency**	**Lead Free**	**DRAM Organization**	**EOL**
Qimonda	HYS72T128020HU-3.7-A	HYB18T512800AF-3.7-A	Qimonda		12/1/06	4	Yes	(64Mx8)*18	
Micron	MT18HTF12872AY-53EB1	MT47H64M8CB-37E	Micron		12/1/06	4	Yes	(64Mx8)*18	
TRS	TRS30309X	HYB18T512800AF37 rev A	Qimonda (Infineon)	M0540LA1 rev 1	1/25/07	4	Yes	(64Mx8)*18	
Dane-Elec	D2D533-072284NG	MT47H64M8B6-37E rev D	Micron	D2U72G rev 1	7/18/07	4	Yes	(64Mx8)*18	

Unbuffered, ECC, DDR2-667 DIMM Modules
1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72T128020HU-3S-A	HYB18T512800AF-3S-A	~ Qimonda (Infineon)		5/19/06	5	Yes	(64Mx8)*18	
Micron	MT18HTF12872AY-667B3	MT47H64M8BT-3	Micron		5/19/06	5	Yes	(64Mx8)*18	
Samsung	M391T2953CZ3-CE6	K4T510830C-ZCE6	Samsung		5/19/06	5	Yes	(64Mx8)*18	
Ventura Technology Group	D2-54CD64LV-555	EDE5108AGBG-6E-E rev G	Elpida	D2U72G na	8/29/06	5	Yes	(64Mx8)*18	
Smart Modular Technologies	SG1287UDR264852 IB	HYB18T512800BF3S rev B	Qimonda (Infineon)	240-7-1 (K0552)	9/1/06	5	Yes	(64Mx8)*18	
Smart Modular Technologies	SG1287UDR264852-SC	K4T51083QC-ZCE6 rev C	Samsung	M391T2953 CZ0 na	9/11/06	5	Yes	(64Mx8)*18	
Smart Modular Technologies	SG1287UDR264852 NA	NT5TU64M8AE-3C rev A	Nanya	PG58G240 NUBUB1RG rev A	9/21/06	5	Yes	(64Mx8)*18	
Smart Modular Technologies	SG1287UDR264852 ES	G64M8XB3IT5X4GSE rev A	Smart	PG58G240 NUBUB1RG rev A	9/25/06	5	Yes	(64Mx8)*18	
Smart Modular Technologies	SG1287UDR264852 SC	K4T51083QC-ZCE6 rev C	Samsung	PG58G240 NUBUB1RG rev A	10/3/06	5	Yes	(64Mx8)*18	
Dataram	DTM63324C	NT5TU64M8AE-3C rev A	Nanya	40031A rev A	10/24/06	5	Yes	(64Mx8)*18	
Kingston	KVR667D2E5/1GI	E5108AGSE(BG)-6E-E rev G	Elpida	2025321-0F1.A00 na	11/28/06	5	Yes	(64Mx8)*18	
ATP Electronics	AJ28K72H8BHE6S	K4T51083QC-ZCE6 rev C	Samsung	SJ240H08K 1 na	12/15/06	5	Yes	(64Mx8)*18	
Ventura Technology Group	D2-54CD64SV-555	K4T51083QC-ZCE6 rev C	Samsung	D2U72G rev 1.0	12/19/06	5	Yes	(64Mx8)*18	
ATP Electronics	AJ28K72G8BHE6S	K4T51083QE-ZCE6 rev E	Samsung	D2U72G V1.0	1/29/07	5	Yes	(64Mx8)*18	
Kingston	KVR667D2E5/1GI	NT5TU64M8BE-3C rev B	Nanya	2025321-0F1.A00 na	5/16/07	5	Yes	(64Mx8)*18	

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Server Board SE7230CA1-E

Unbuffered, Non-ECC, DDR2-400 DIMM Modules
1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-533 DIMM Modules
1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
Dane-Elec	D2D533-064284NG	EDE5108AG-5C-E rev G	Elpida	D2U64E na	7/23/07	4	Yes	(64Mx8)*18	

Unbuffered, Non-ECC, DDR2-667 DIMM Modules
1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

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Server Board SE7230CA1-E

Unbuffered, ECC, DDR2-400 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, ECC, DDR2-533 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
Kingston	KVR533D2E4/2GI	MT47H128M8HQ-3 rev E	Micron	2025321-0F1.A00 na	4/18/07	4	Yes	(128Mx8)*18	
Kingston	KVR533D2E4/2GI	E1108AB-6E-E rev B	Elpida	2025321-0F1.A00 na	4/23/07	4	Yes	(128Mx8)*18	
Dane-Elec	D2D533-072564TG	MT47H128M8BT-37E rev A	Micron	D2U72G rev 1	7/17/07	4	Yes	(128Mx8)*18	

Unbuffered, ECC, DDR2-667 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL
Samsung	M391T5663AZ3-CE6	K4T1G084QA-ZCE6	Samsung		5/19/06	5		(128Mx8)*18	
Hynix	HYMP125U72P8-Y5	HY5PS1G831FP-Y5	Hynix		5/19/06	5		(128Mx8)*18	
TRS	TRS30321X	E1108AB-6E-E rev B	Elpida	M0540LA1 rev 1	1/10/07	5	Yes	(128Mx8)*18	
ATP Electronics	AJ56K72G8BJE6S	K4T1G084QA-ZCE6 rev A	Samsung	SJ240G08K1 na	3/9/07	5	Yes	(128Mx8)*18	
Smart Modular Technologies	SG2567UDR212852IB	HYB18T1G800BF-3S rev B	Qimonda	PG58G240NUBUB1RG rev A	5/22/07	5	Yes	(128Mx8)*18	
ATP Electronics	AJ56K72G8BJE6M	MT47H128M8HQ-3 rev E	Micron	SJ240G08K1 na	11/5/07	5	Yes	(128Mx8)*18	

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Unbuffered, Non-ECC, DDR2-400 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-533 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR2-667 DIMM Modules
2GB Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Lead Free	DRAM Organization	EOL

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Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpusa.com/	Tel (1) 408-732-5000, ext 5858 Fax 408-732-5893 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpusa.com/	Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA phenke@dataram.com Peter Jauss, +49-69-680-9070 in EMEA pjauss@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
Infineon	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itaucom.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Keri Albers 888 466 3853 ext. 307 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/"http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com

Vendor Name	Web URL	Vendor Direct Sales Info
Peripheral Enhancements	http://www.peripheral.com/	
PNY	http://www.pny.com/internet_explorer/LPB.HTML	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	http://www.smartm.com	Leo Alafriz 949-753-0116 ext. 125 leo.alafriz@smartm.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http:/www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gründl, Pho.: +49(0)89/94553234, Fax.: +49(0)89/94553293, agruendl@trs-space.de
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 724-8700 ext. 103
Viking InterWorks	http://www.vikinginterworks.com	Adrian Proctor Tel: 949-643-7255 adrian.proctor@sanmina-sci.com
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.